

Fig. 1

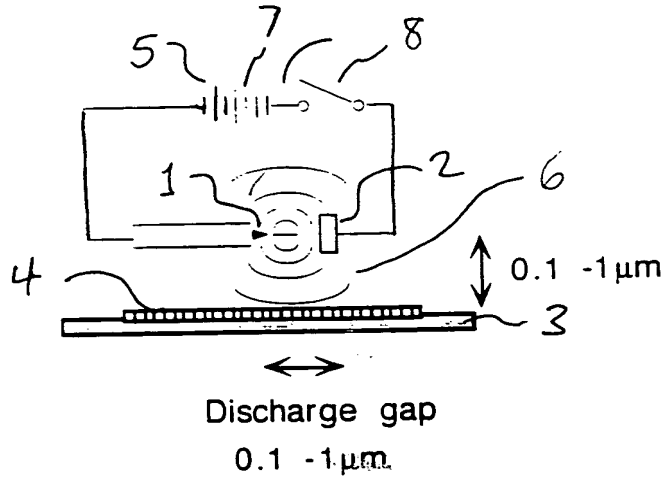


Fig. 2

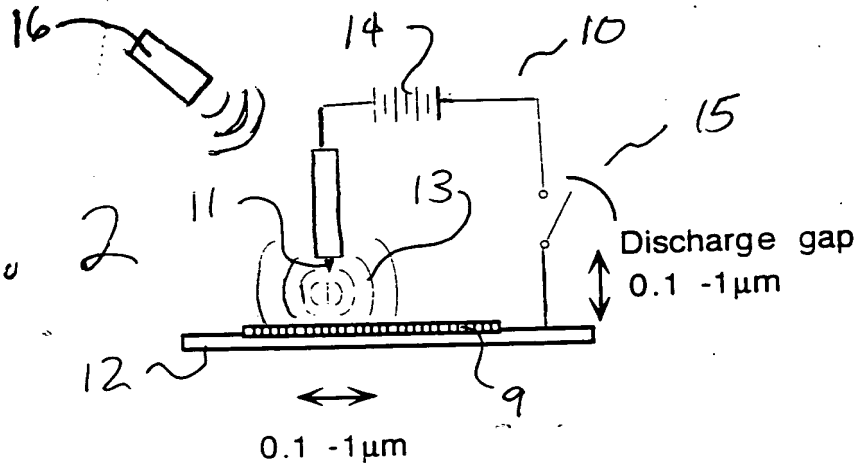


Fig. 6

Liquid	Atomic Number	Melt. point [°K]	Boiling point [°K]	Critical Temp. [°K]	Critical Pressure [Bar]	Heat of Vaporisat. [$10^3 \text{ JK}^{-1} \text{ kg}^{-1}$]	Heat Capacity [$\text{JK}^{-1} \text{ kg}^{-1}$]
H ₂	1	13.8	20.3	33.3	17	310	14200
N ₂	7	63.0	77.4	126.2	34	200	1040
O ₂	8	54.8	90.2	154.6	51	213	920
F ₂	9	55.5	85.4	144.0	57	316	750
Ne	10	24.5	27.0	54.0	27	86	1030
Ar	18	83.8	87.3	150.8	48	158	520
Cl ₂	17	171.6	239.1	417.0	77	282	500
Kr	36	116.6	120	209.4	55	108	-
Xe	54	161.3	165.1	289.7	59	102	-

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Fig. 3

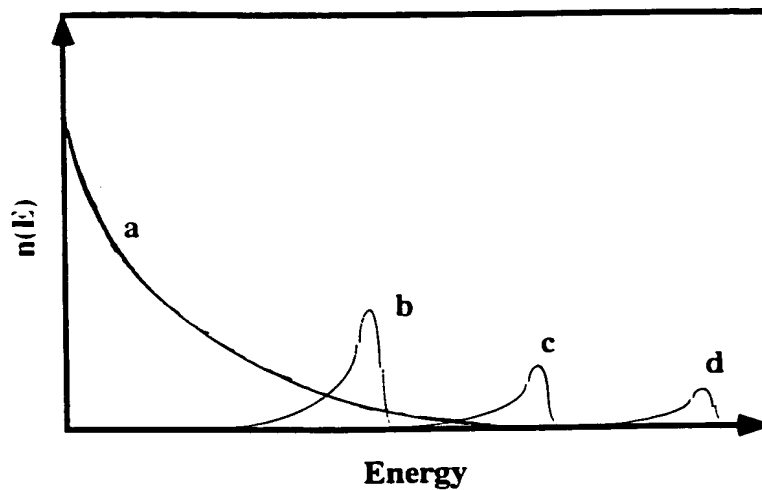


Fig. 4

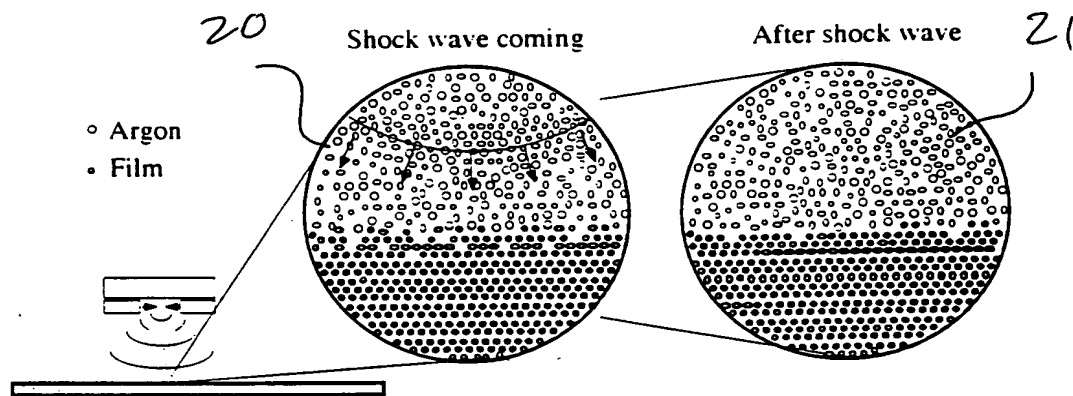
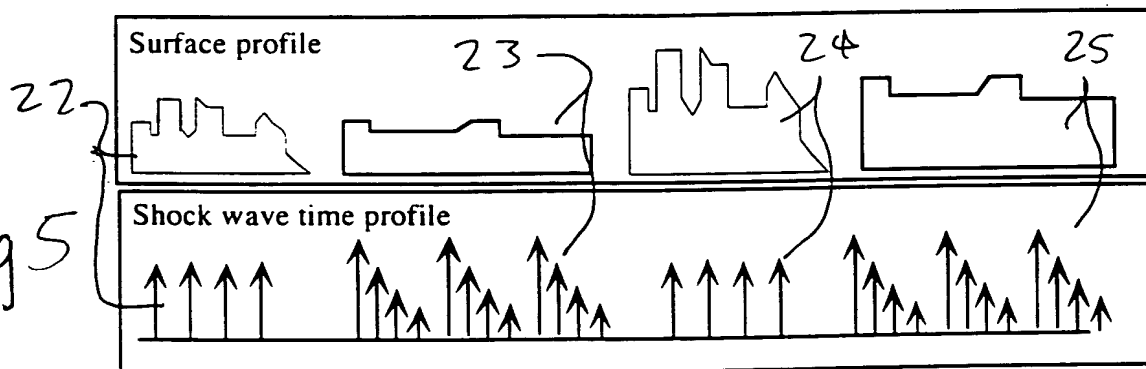


Fig 5



1th Deposition stage 1st Annealing stage 2nd Deposition stage 2nd Annealing stage
fluxing of material fluxing of material

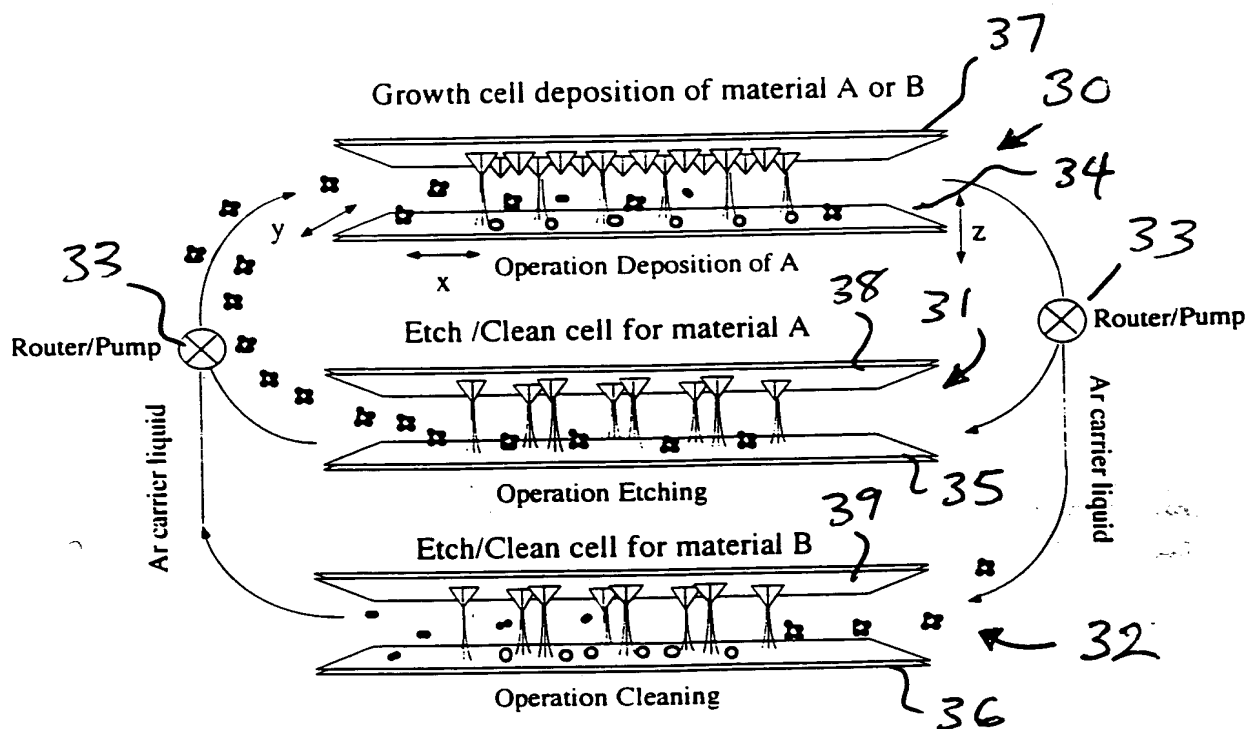


Fig. 7

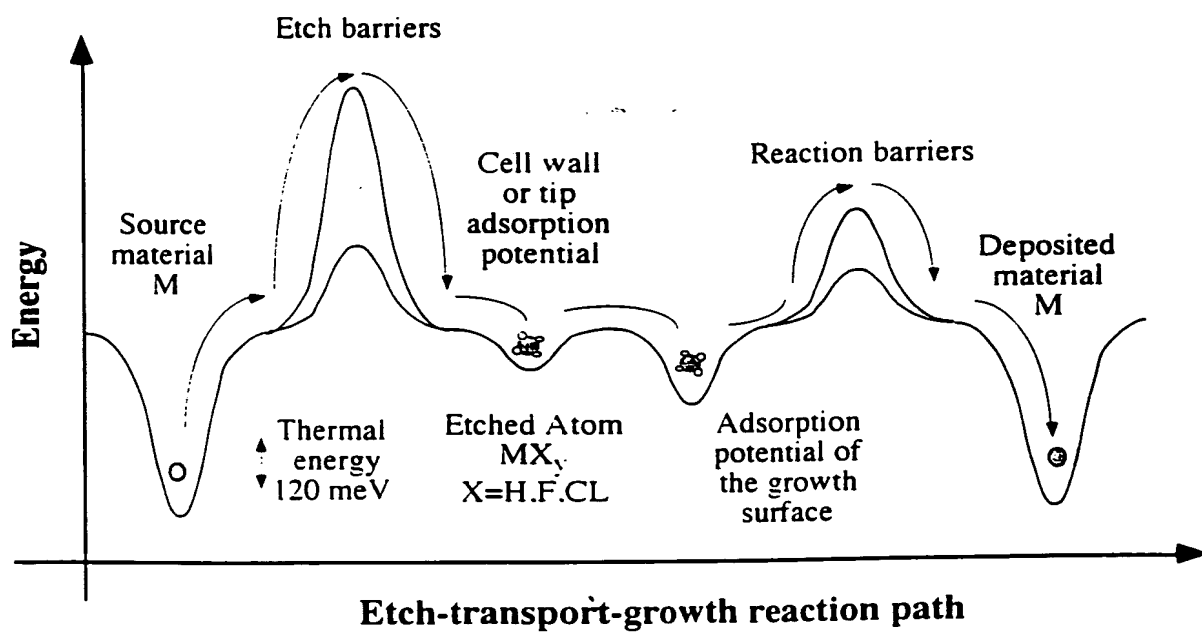


Fig. 10

Fig. 8

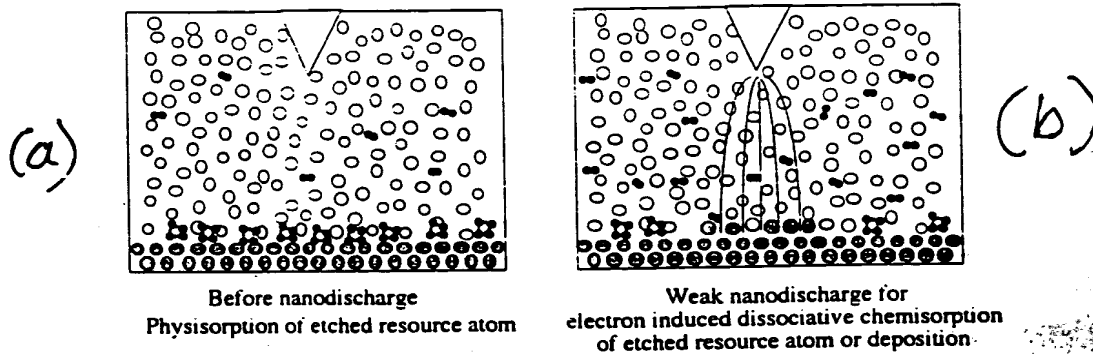
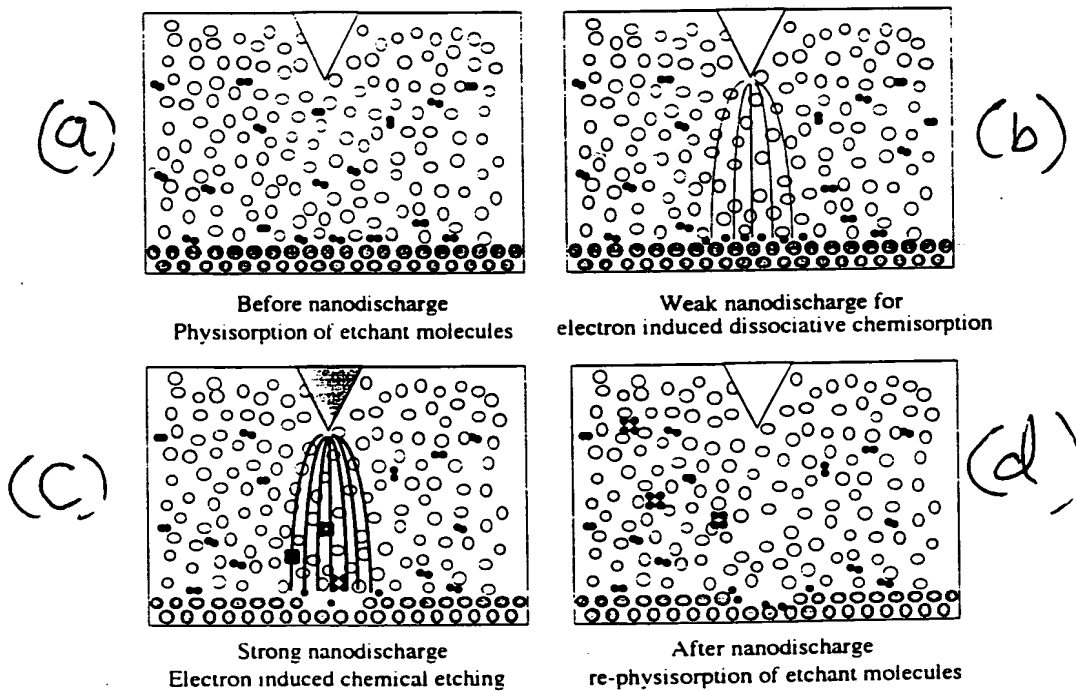


Fig. 9

○ Argon ○ Resource atom ■ Etched resource atom
● Etchant molecule



T=80-150°K Pressure = 1.0 - 50 Bar

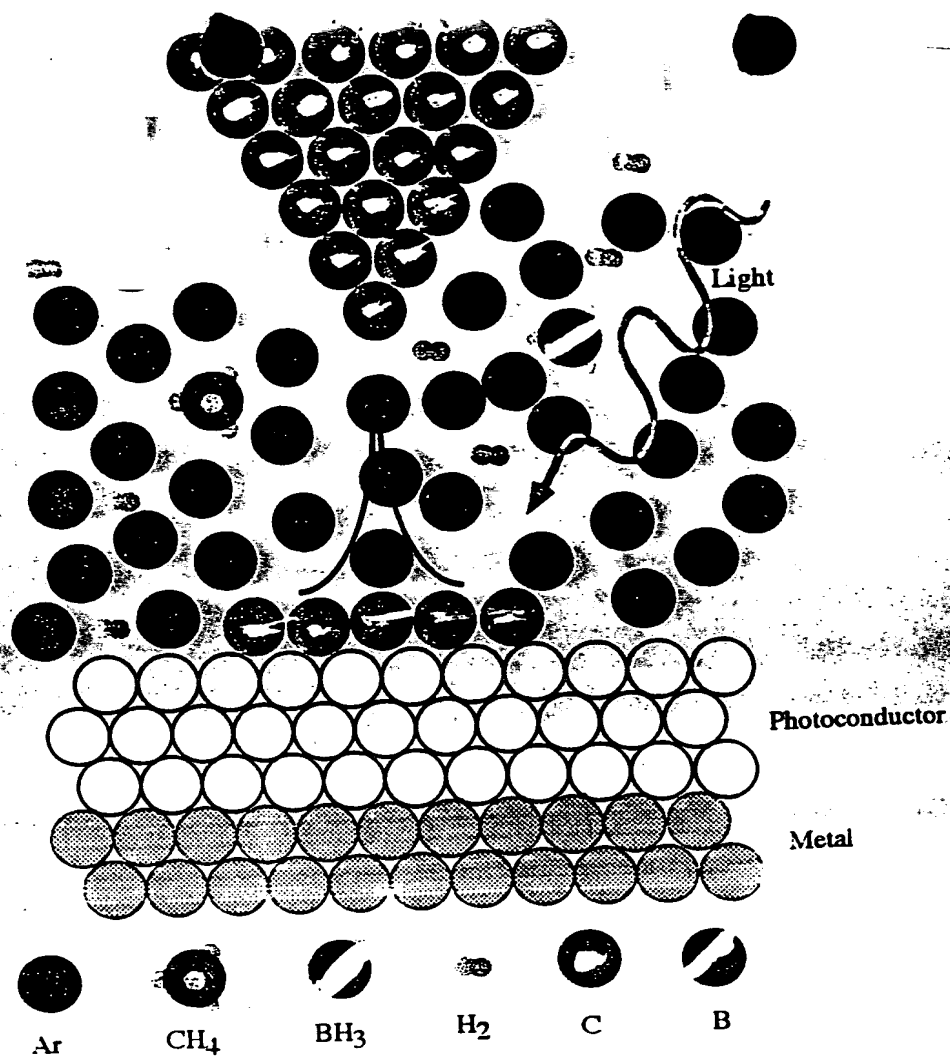


Fig. 11

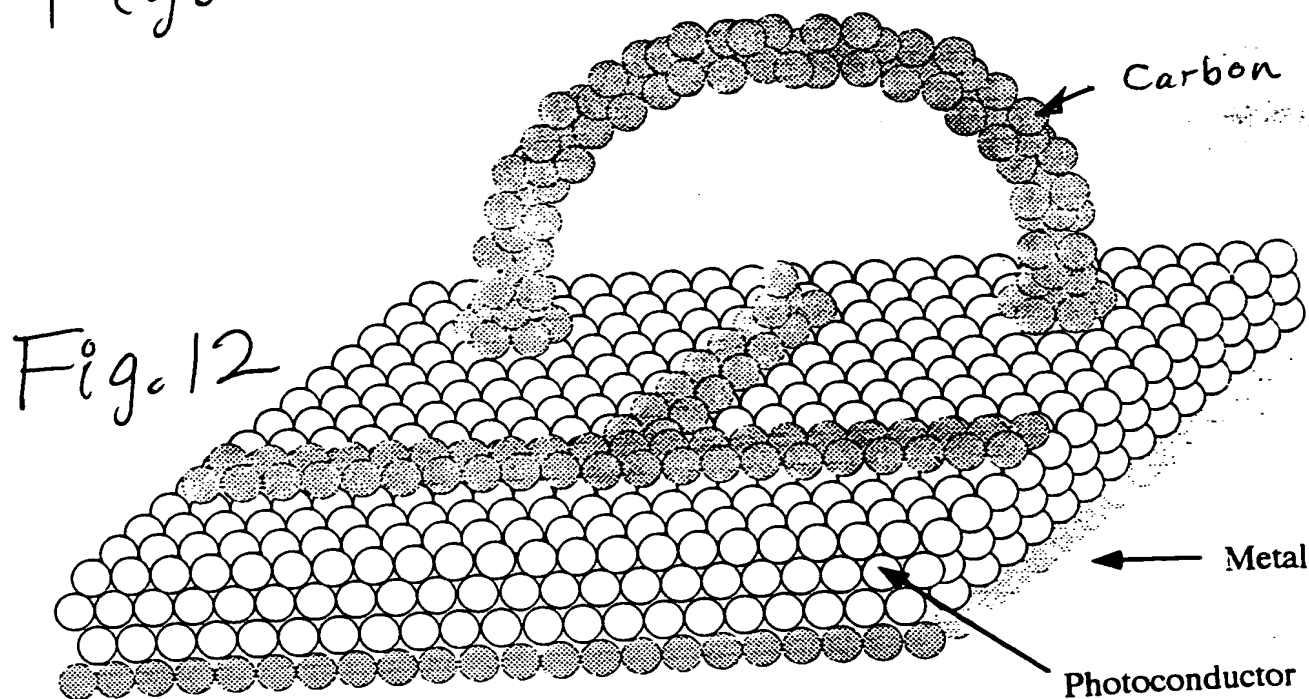


Fig. 12

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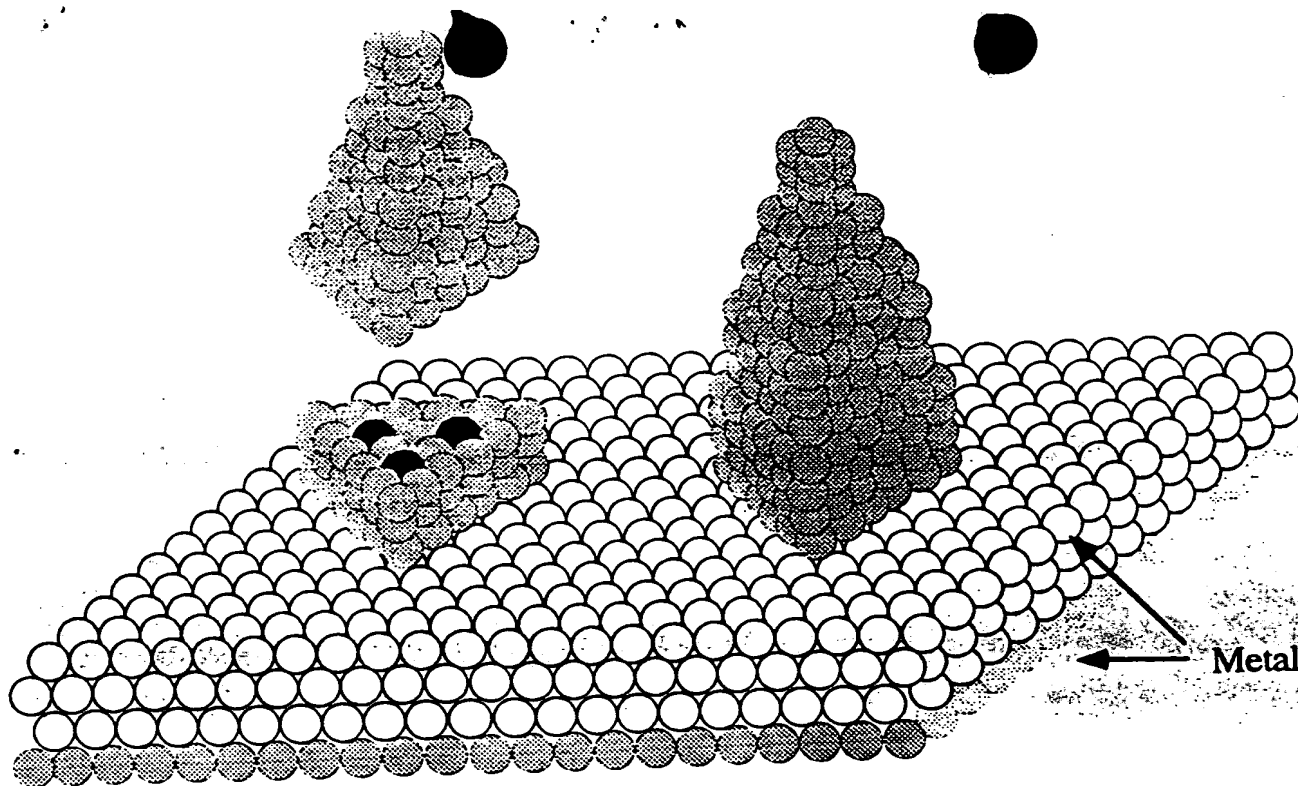


Fig. 13

C B

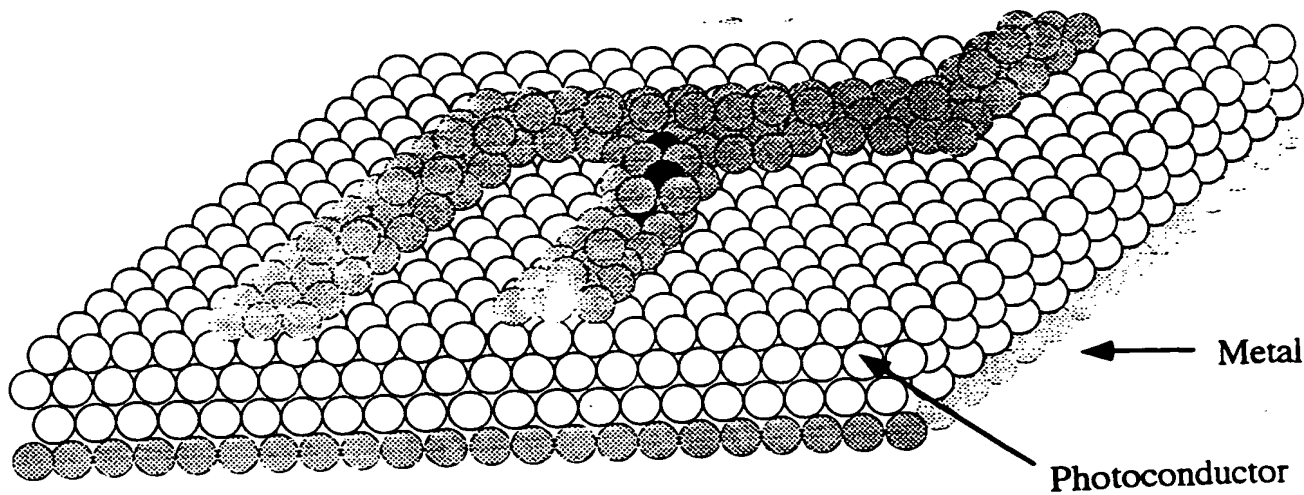


Fig. 14

C B